Product End-of-Life Disassembly Instructions

Product Category: Personal Computers
Marketing Name / Model [List multiple models if applicable.]
HP Compaq 8100 Elite Convertible Minitower Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	PSU Fan, System Fan, Cooler Fan	3
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

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Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
Rear Fan	Fan frame, Delta	42.5g	>PBT-I-GF25 FR(40)<	
	Fan frame, ADDA	44g	>PBT-I-GF25 FR(40)<	
	Fan frame, AVC	37.75g	>PBT-I-GF25 FR(40)<	
	Fan frame, FXN	42.3g	>PBT-I-GF25 FR(40)<	
Cooler Fan	Fan frame, Delta	33.25g	>PBT-I-GF25 FR(40)<	
	Fan frame, AVC	29.5g	>PBT-I-GF25 FR(40)<	
Bezel	main bezel	242.47g	>ABS<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	T-15
Micro shear	170II
Screwdriver	PH1
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel.(see Figure 1 below)
2. Disconnect the cables from the board.(see Figure 2-5 below)
3. Remove the HDD from cage.(see Figure 6 below)
4. Remove PSU from chassis.(see Figure 7&8 below)
5. Remove system fan.(see Figure 9&10 below)
6. Remove the Memory card from the board.(see Figure 11 below)
7. Remove the CPU from the board .(see Figure 12-14 below)
8. Remove the battery from the system board.(see Figure 15 below)
9. Remove M/B from chassis.(see Figure 16&17 below)
10. Remove front panel.(see Figure 18 below)
11. Remove ODD from chassis.(see Figure 19 below)
12. Remove PSU cover.(see Figure 20&21 below)
13. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 22-26 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

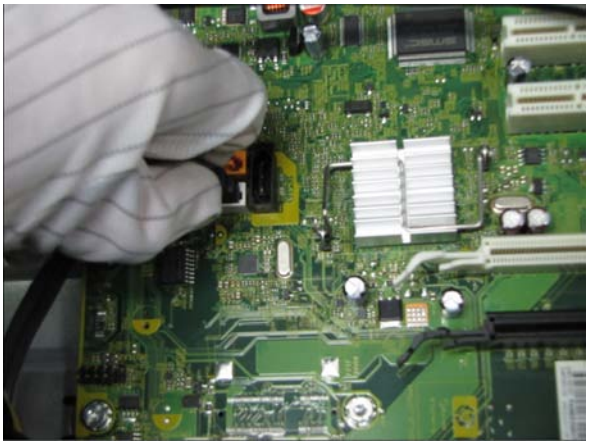
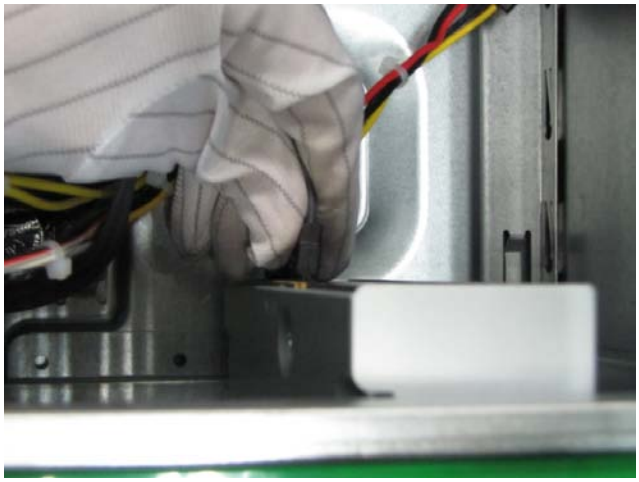
Figure 1 Remove the side panel: 	Figure 2 Disconnect the cables from the board 
Figure 3 Disconnect PSU cables from the board 	Figure 4 Disconnect the cables from the ODD 

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Figure 5 Disconnect the cables from the HDD

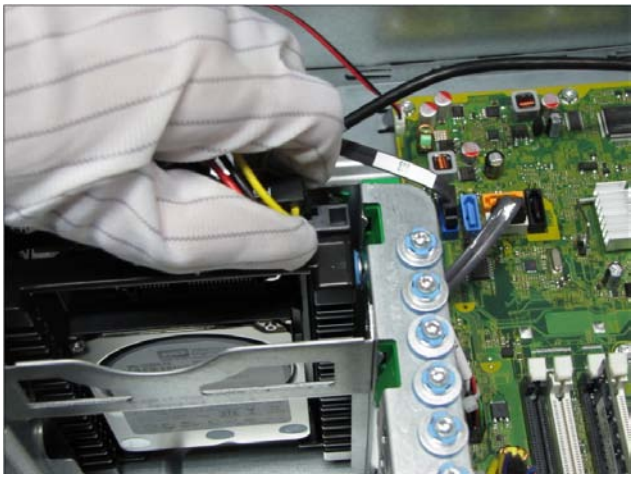

Figure 6 Remove the HDD from cage

Figure 7 Loose the screws from PSU

Figure 8 Press the baffle and slide the PSU

Figure 9 Loose the screws from system fan

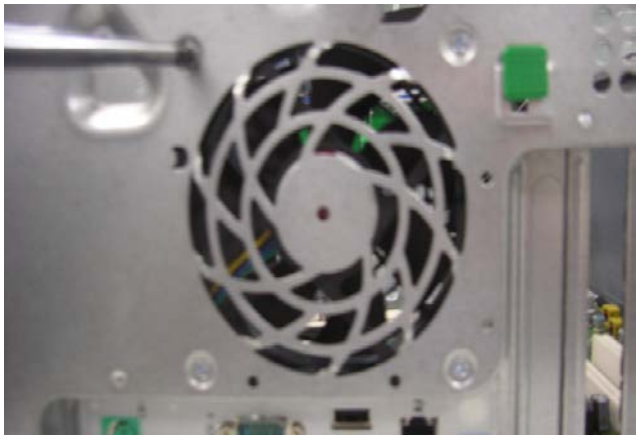

Figure 10 Remove system fan

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Figure 11 Remove the Memory card from the board

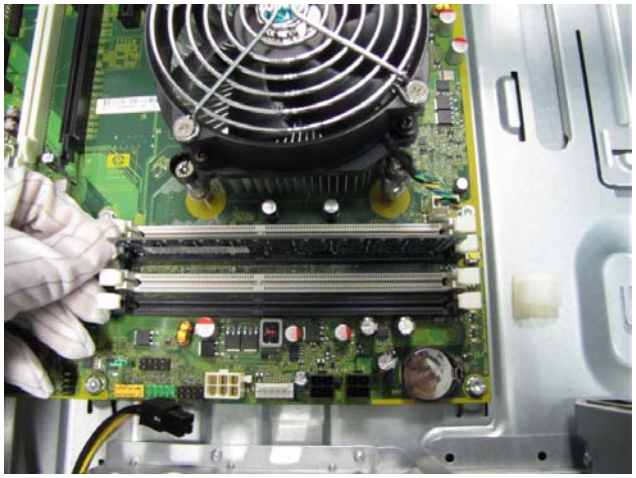

Figure12 Loose the screws and remove CPU fan

Figure 13 Rotate the handle and open it up

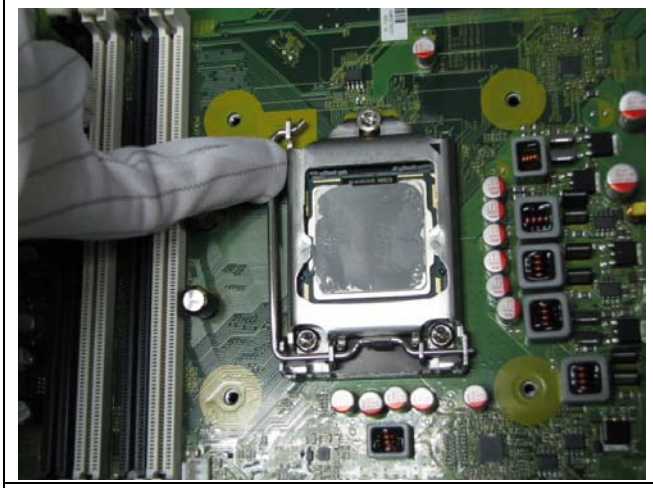

Figure 14 Remove the CPU from the board

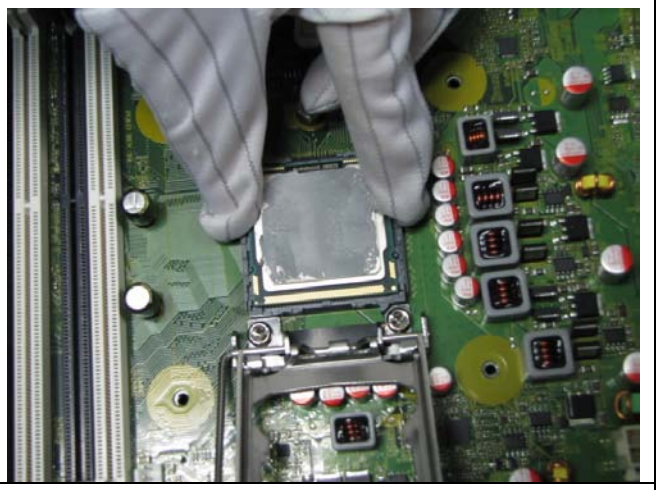

Figure 15 Remove the battery from the system board

Figure 16 Loose the screws from board

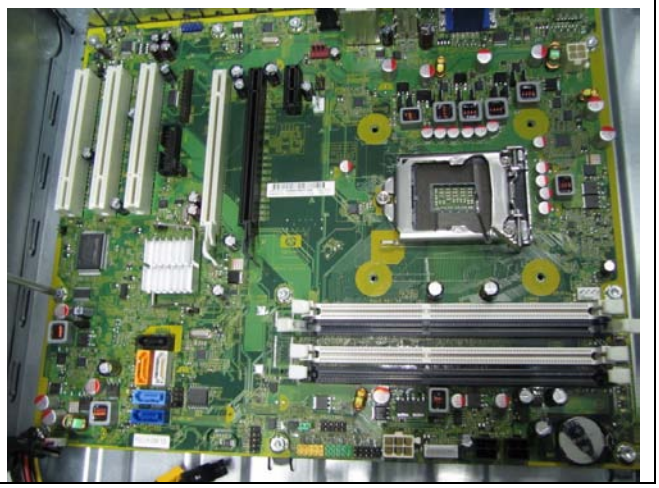

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Figure 17 Remove M/B from chassis

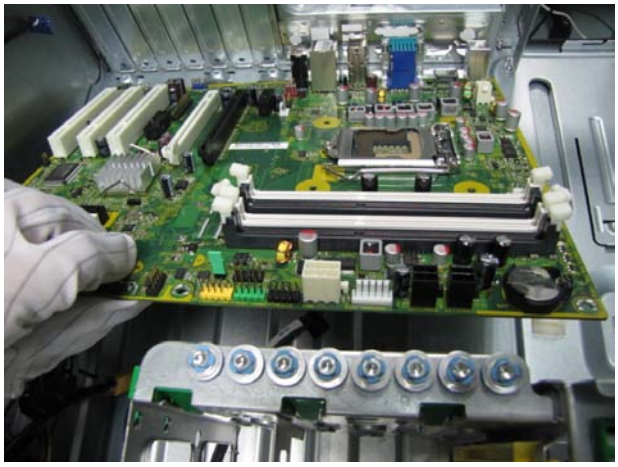

Figure 18 Remove front panel

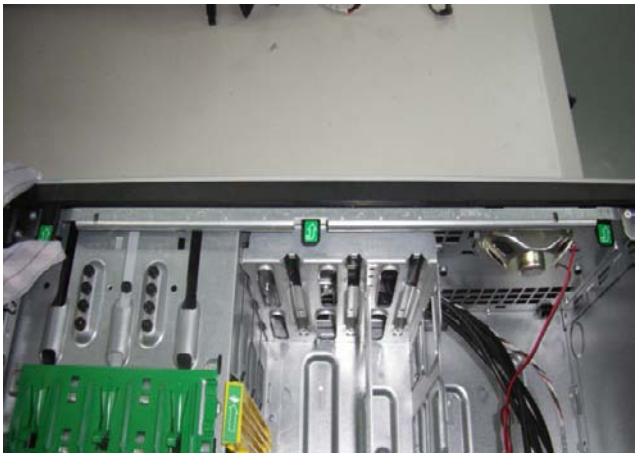

Figure19 Remove ODD from chassis

Figure 20 Remove the screws on the PSU chassis

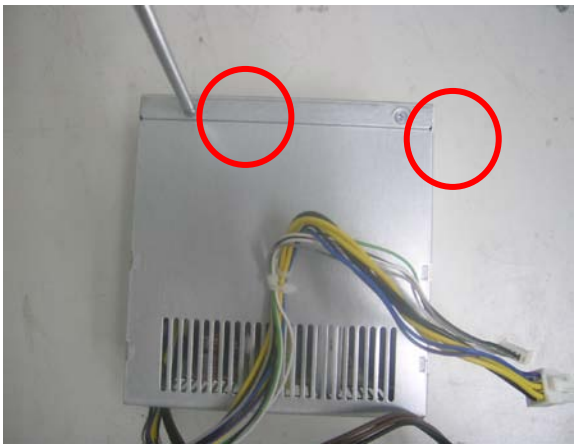

Figure 21 Lift the cover off the power supply

Figure 22 Remove the four screws on the board

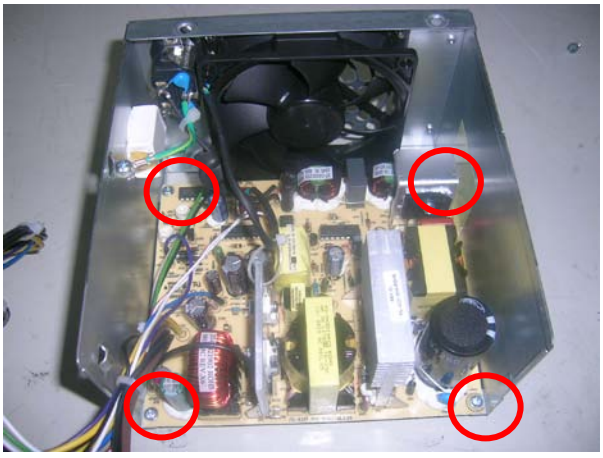

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Figure 23 Using Soldering Iron, heat the solder of the cables which connect to the PCA, then remove them

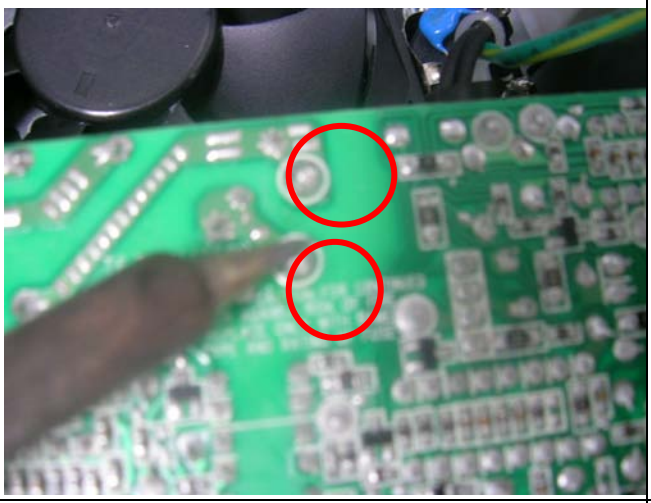

Figure 24 Remove the power supply PCA from the power supply chassis

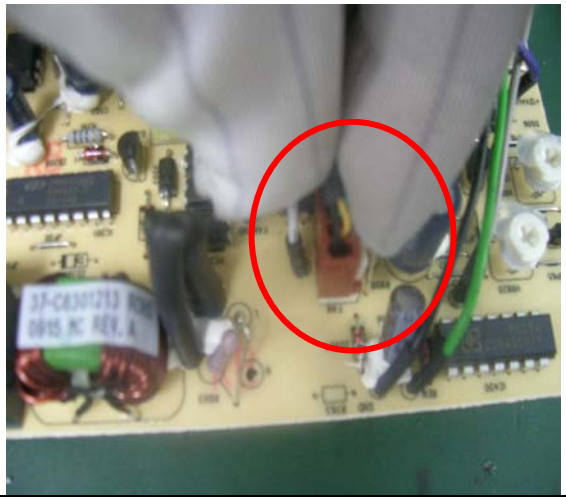

Figure 25 Heat the solder of Electrolytic Capacitors

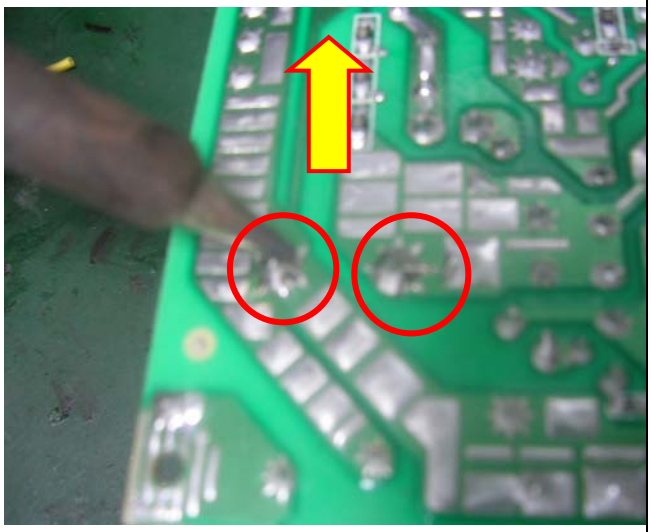

Figure 26 Remove the Electrolytic Capacitors

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